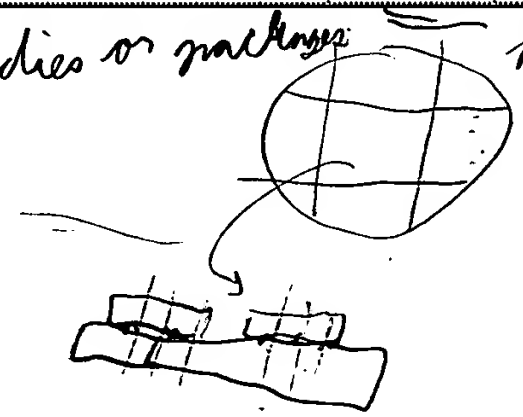


	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	253834 8	(underfill or fill\$6 or inject\$6)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/23 14:03
2	BRS	L2	190472 0	wafer\$3 or substrate\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/23 14:04
3	BRS	L3	19864	"flip chip"	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/23 14:04
4	BRS	L4	366590 5	dic\$6 or separat\$6 or singulat\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/23 14:05
5	BRS	L5	894488	gap\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/23 14:05

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	186901 2	chip\$3 or die\$3 or dice or packag\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/23 14:06
7	BRS	L7	77011	1 near8 5	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/23 14:06
8	BRS	L8	186	7 same 2 same 4 same 6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/23 14:08
9	BRS	L9	92	8 and 3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/02/23 14:09

L6 → L28 chips! or die or dies or packages
 bond
 encaps
 chips - - -
 substrates - - -
 dicing - - -
 encapsulating / resin - - -
 multiple or many
 or numbers or several



plural
 1st dicing
 of wafer

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	112142	(substrate or substrates or wafer or wafers) near8 (chip or chips or die or dies or dice or packages)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 13:11
2	BRS	L2	360878 7	(multiple or many or several or multichip\$3 or multi-chip\$3 or (multi adj chip\$3)) hmc m	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 13:12
3	BRS	L3	183987 1	encapsulat\$4 or fill\$4 or underfill\$4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 13:13
4	BRS	L4	358055 0	dic\$4 or singulat\$4 or separat\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 10:21
5	BRS	L5	533	1 same 2 same 3 same 4	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 10:21

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	BRS	L6	109210 5	chip or chips or die or dies or dice or packages	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 13:11
7	BRS	L7	190901 3	(substrates or substrate or wafer or wafers)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 13:11
8	BRS	L8	351621 6	dicing or singulat\$6 or separat\$6	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 13:12
9	BRS	L9	10555	2 near8 6 near8 7	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 13:13
10	BRS	L10	1810	9 same 8	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 13:13

	Type	L #	Hits	Search Text	DBs	Time Stamp
11	BRS	L11	147	10 same 3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2004/03/01 13:13